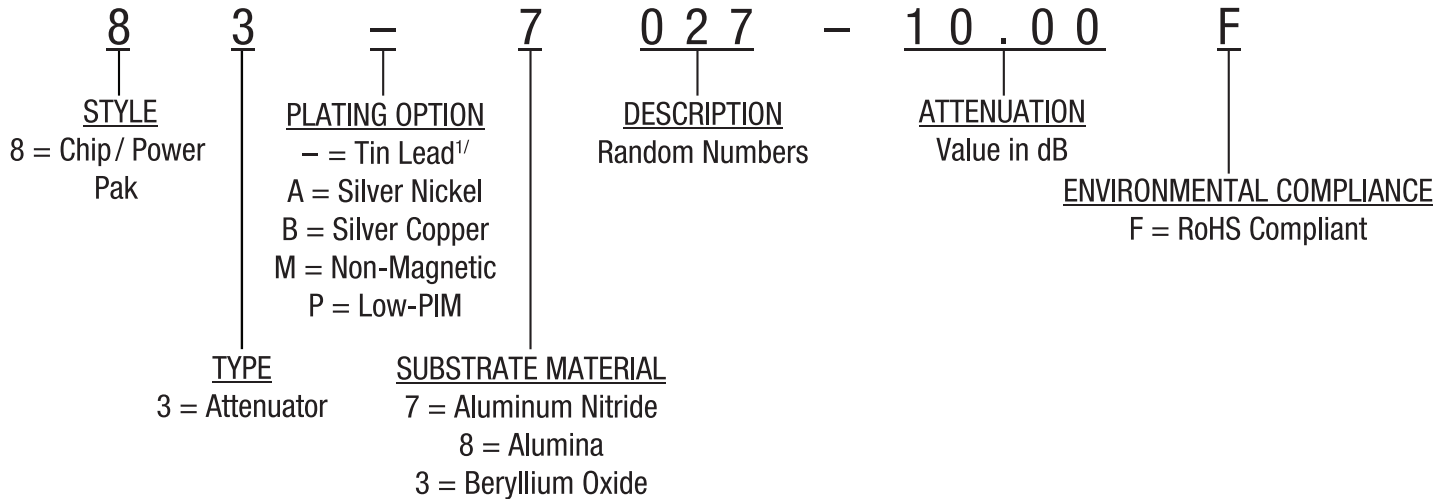


83 Series

SMT Chip Attenuator



Part Numbering Code



^{1/}Not RoHS Compliant

Product Information Table

Power	Frequency	VSWR	L		W		H		Part Series #	Figure #
	GHz	Max:1	mm [inches]							
5	3.0	1.50	4.44	[0.175]	5.08	[0.200]	1.02	[0.040]	83 3995*	1
5	2.0	1.30	3.81	[0.150]	4.45	[0.175]	1.02	[0.040]	83 8999*	1
7	3.0	1.35	5.97	[0.235]	2.87	[0.113]	0.64	[0.025]	83 8054*	3
10	3.0	1.50	6.35	[0.250]	6.35	[0.250]	1.02	[0.040]	83 7999*	1
10	2.0	1.35	5.08	[0.200]	2.54	[0.100]	1.02	[0.040]	83 7014*	3
10	3.0	1.50	6.35	[0.250]	6.35	[0.250]	1.02	[0.040]	83 3999*	1
20	3.0	1.50	9.53	[0.375]	9.53	[0.375]	1.02	[0.040]	83 7027*	1
20	6.0	1.40	5.08	[0.200]	4.45	[0.175]	0.64	[0.025]	83 7044*	1
25	2.0	1.40	9.53	[0.375]	9.53	[0.375]	1.02	[0.040]	83 3998*	1
20	3.0	1.22	5.08	[0.200]	2.54	[0.100]	0.38	[0.015]	83 7046*	3
50	3.0	1.22	6.35	[0.250]	6.35	[0.250]	0.64	[0.025]	83 7047*	2
75	2.4	1.25	7.62	[0.250]	6.35	[0.250]	1.02	[0.040]	83 7012* /2	3
120	2.4	1.20	5.84	[0.230]	8.89	[0.350]	1.02	[0.040]	83 7026*	2

* is a place holder. See part number configurations to complete the part number.

/2 only available in 30dB

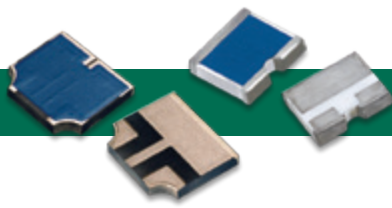
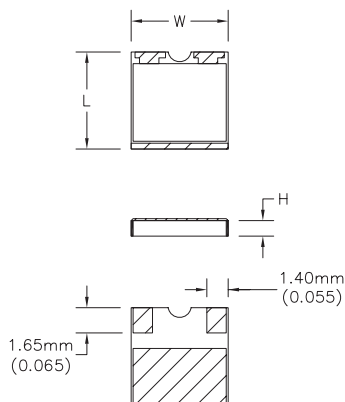


Figure 1

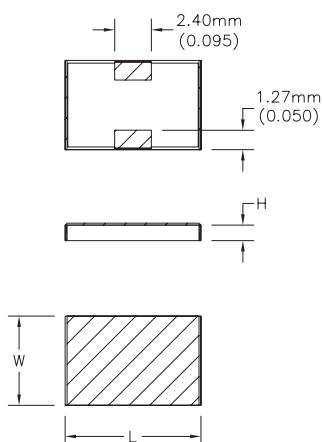


The 83 series surface mount chip attenuators are designed for direct installation on printed circuit boards and manufactured using thin film process. Edge metallization on two sides forms the solder fillets for stronger attachment, easier inspection, and increased heat removal area. The devices are available in Alumina, Aluminum Nitride (AlN) or BeO. RoHS-compliant versions are available.

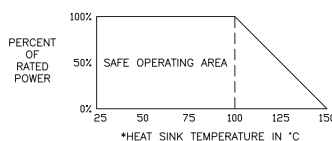
Specifications

Impedance	50 Ohms
Frequency Range	DC to 18 GHz
VSWR (Typical)	1.30
Power Rating	5 - 120 Watts
Operating Temperature	-55°C to 150°C
Substrate	Alumina, BeO and AlN
Resistive Material	Thin Film
Terminal Material	Thick Film, Nickel Barrier, Solder Plated or RoHS, Gold and Wire Bondable Options Available

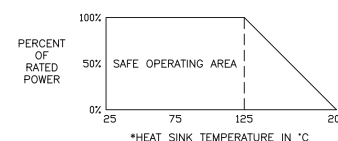
Figure 2



Power Rating and Derating



Alternative Derating Available Upon Request



*The heat sink is defined as the surface that the Component is attached to, ie. chassis or printed circuit board.

Figure 3

